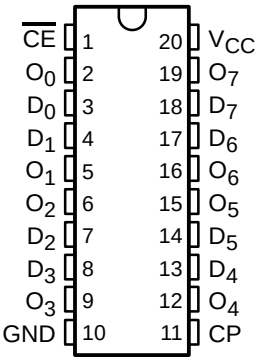
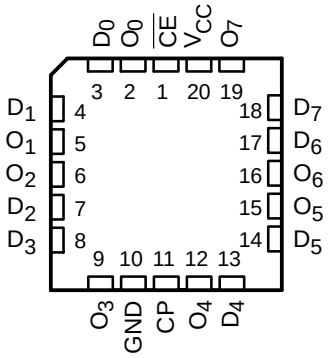
- **Function, Pinout, and Drive Compatible With FCT and F Logic**
- **Reduced $V_{OH}$ (Typically = 3.3 V) Versions of Equivalent FCT Functions**
- **Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics**
- **$I_{off}$ Supports Partial-Power-Down Mode Operation**
- **Matched Rise and Fall Times**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**
- **Fully Compatible With TTL Input and Output Logic Levels**
- **Clock Enable for Address and Data Synchronization Application**
- **Eight Edge-Triggered D-Type Flip-Flops**
- **CY54FCT377T**
  - **32-mA Output Sink Current**
  - **12-mA Output Source Current**
- **CY74FCT377T**
  - **64-mA Output Sink Current**
  - **32-mA Output Source Current**

**SN74FCT377T . . . Q OR SO PACKAGE**
**(TOP VIEW)**




**SN54FCT377T . . . L PACKAGE**
**(TOP VIEW)**




## description

The ’FCT377T devices have eight triggered D-type flip-flops with individual data (D) inputs. The common buffered clock (CP) inputs load all flip-flops simultaneously when the clock-enable ($\overline{CE}$) input is low. The register is fully edge triggered. The state of each D input at one setup time before the low-to-high clock transition is transferred to the corresponding flip-flop output (O). $\overline{CE}$ must be stable only one setup time prior to the low-to-high clock transition for predictable operation.

These devices are fully specified for partial-power-down applications using $I_{off}$. The $I_{off}$ circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

## ORDERING INFORMATION

| $T_A$ | PACKAGE† | | SPEED (ns) | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|---|---|---|---|---|---|
| –40°C to 85°C | QSOP – Q | Tape and reel | 5.2 | CY74FCT377CTQCT | FCT377C |
| | SOIC – SO | Tube | 5.2 | CY74FCT377CTSOC | FCT377C |
| | | Tape and reel | 5.2 | CY74FCT377CTSOCT | |
| | QSOP – Q | Tape and reel | 7.2 | CY74FCT377ATQCT | FCT377A |
| | SOIC – SO | Tube | 7.2 | CY74FCT377ATSOC | FCT377A |
| | | Tape and reel | 7.2 | CY74FCT377ATSOCT | |
| | QSOP – Q | Tape and reel | 13 | CY74FCT377TQCT | FCT377 |
| –55°C to 125°C | LCC – L | Tube | 5.5 | CY54FCT377CTLMB | |
| | | Tube | 8.3 | CY54FCT377ATLMB | |

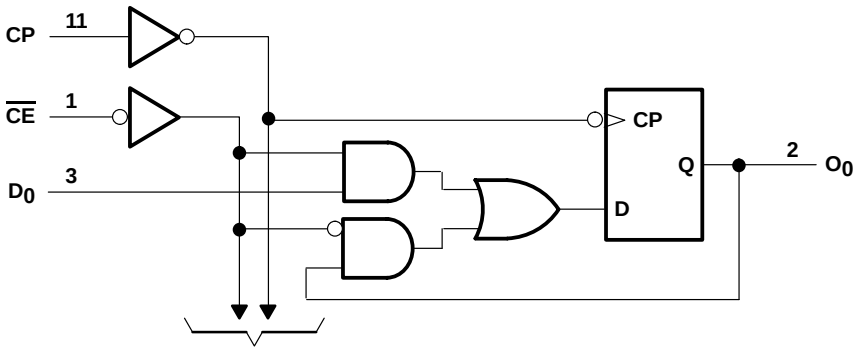
† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

**FUNCTION TABLE**

| INPUTS | | | OUTPUT | OPERATING |
|---|---|---|---|---|
| CP | $\overline{CE}$ | D | O | MODE |
| ↑ | l | h | H | Load 1 |
| ↑ | l | l | L | Load 0 |
| ↑ | h | X | No change | Hold |
| X | H | X | | |

H = High logic level, h = High logic level one setup time prior to the low-to-high clock transition, L = Low logic level, l = Low logic level one setup time prior to the low-to-high clock transition, X = Don't care, ↑ = Low-to-high clock transition

## logic diagram



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential . . . . . –0.5 V to 7 V
DC input voltage range . . . . . –0.5 V to 7 V
DC output voltage range . . . . . –0.5 V to 7 V
DC output current (maximum sink current/pin) . . . . . 120 mA
Package thermal impedance, $\theta_{JA}$ (see Note 1): Q package . . . . . 68°C/W
SO package . . . . . 58°C/W
Ambient temperature range with power applied, $T_A$ . . . . . –65°C to 135°C
Storage temperature range, $T_{stg}$ . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 2)

| | | CY54FCT377T | | | CY74FCT377T | | | UNIT |
|---|---|---|---|---|---|---|---|---|
| | | MIN | NOM | MAX | MIN | NOM | MAX | |
| $V_{CC}$ | Supply voltage | 4.5 | 5 | 5.5 | 4.75 | 5 | 5.25 | V |
| $V_{IH}$ | High-level input voltage | 2 | | | 2 | | | V |
| $V_{IL}$ | Low-level input voltage | | | 0.8 | | | 0.8 | V |
| $I_{OH}$ | High-level output current | | | –12 | | | –32 | mA |
| $I_{OL}$ | Low-level output current | | | 32 | | | 64 | mA |
| $T_A$ | Operating free-air temperature | –55 | | 125 | –40 | | 85 | °C |

NOTE 2: All unused inputs of the device must be held at $V_{CC}$ or GND to ensure proper device operation.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | CY54FCT377T | | | CY74FCT377T | | | UNIT |
|---|---|---|---|---|---|---|---|---|---|
| | | | MIN | TYP† | MAX | MIN | TYP† | MAX | |
| $V_{IK}$ | $V_{CC}$ = 4.5 V, | $I_{IN}$ = –18 mA | | –0.7 | –1.2 | | | | V |
| | $V_{CC}$ = 4.75 V, | $I_{IN}$ = –18 mA | | | | | –0.7 | –1.2 | |
| $V_{OH}$ | $V_{CC}$ = 4.5 V, | $I_{OH}$ = –12 mA | 2.4 | 3.3 | | | | | V |
| | $V_{CC}$ = 4.75 V | $I_{OH}$ = –32 mA | | | | 2 | | | |
| | | $I_{OH}$ = –15 mA | | | | 2.4 | 3.3 | | |
| $V_{OL}$ | $V_{CC}$ = 4.5 V, | $I_{OL}$ = 32 mA | | 0.3 | 0.55 | | | | V |
| | $V_{CC}$ = 4.75 V, | $I_{OL}$ = 64 mA | | | | | 0.3 | 0.55 | |
| $V_{hys}$ | All inputs | | | 0.2 | | | 0.2 | | V |
| $I_I$ | $V_{CC}$ = 5.5 V, | $V_{IN}$ = $V_{CC}$ | | | 5 | | | | µA |
| | $V_{CC}$ = 5.25 V, | $V_{IN}$ = $V_{CC}$ | | | | | | 5 | |
| $I_{IH}$ | $V_{CC}$ = 5.5 V, | $V_{IN}$ = 2.7 V | | | ±1 | | | | µA |
| | $V_{CC}$ = 5.25 V, | $V_{IN}$ = 2.7 V | | | | | | ±1 | |
| $I_{IL}$ | $V_{CC}$ = 5.5 V, | $V_{IN}$ = 0.5 V | | | ±1 | | | | µA |
| | $V_{CC}$ = 5.25 V, | $V_{IN}$ = 0.5 V | | | | | | ±1 | |
| $I_{OS}$‡ | $V_{CC}$ = 5.5 V, | $V_{OUT}$ = 0 V | –60 | –120 | –225 | | | | mA |
| | $V_{CC}$ = 5.25 V, | $V_{OUT}$ = 0 V | | | | –60 | –120 | –225 | |
| $I_{off}$ | $V_{CC}$ = 0 V, | $V_{OUT}$ = 4.5 V | | | ±1 | | | ±1 | µA |
| $I_{CC}$ | $V_{CC}$ = 5.5 V, | $V_{IN}$ ≤ 0.2 V, $V_{IN}$ ≥ $V_{CC}$ – 0.2 V | | 0.1 | 0.2 | | | | mA |
| | $V_{CC}$ = 5.25 V, | $V_{IN}$ ≤ 0.2 V, $V_{IN}$ ≥ $V_{CC}$ – 0.2 V | | | | | 0.1 | 0.2 | |
| $\Delta I_{CC}$ | $V_{CC}$ = 5.5 V, $V_{IN}$ = 3.4 V§, $f_1$ = 0, Outputs open | | | 0.5 | 2 | | | | mA |
| | $V_{CC}$ = 5.25 V, $V_{IN}$ = 3.4 V§, $f_1$ = 0, Outputs open | | | | | | 0.5 | 2 | |

† Typical values are at $V_{CC}$ = 5 V, $T_A$ = 25°C.

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, $I_{OS}$ tests should be performed last.

§ Per TTL-driven input ($V_{IN}$ = 3.4 V); all other inputs at $V_{CC}$ or GND

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)**

| PARAMETER | TEST CONDITIONS | | | CY54FCT377T | | | CY74FCT377T | | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|
| | | | | MIN | TYP† | MAX | MIN | TYP† | MAX | |
| $I_{CCD}$¶ | $V_{CC}$ = 5.5 V, Outputs open, One bit switching at 50% duty cycle, $\overline{CE}$ = GND, $V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V | | | | 0.06 | 0.12 | | | | mA/ MHz |
| | $V_{CC}$ = 5.25 V, Outputs open, One bit switching at 50% duty cycle, $\overline{CE}$ = GND, $V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V | | | | | | | 0.06 | 0.12 | |
| $I_C$# | $V_{CC}$ = 5.5 V, Outputs open, $f_0$ = 10 MHz, $\overline{CE}$ = GND | One bit switching at $f_1$ = 5 MHz at 50% duty cycle | $V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V | | 0.7 | 1.4 | | | | mA |
| | | | $V_{IN}$ = 3.4 V or GND | | 1.2 | 3.4 | | | | |
| | | Eight bits switching at $f_1$ = 2.5 MHz at 50% duty cycle | $V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V | | 1.6 | 3.2‖ | | | | |
| | | | $V_{IN}$ = 3.4 V or GND | | 3.9 | 12.2‖ | | | | |
| | $V_{CC}$ = 5.25 V, Outputs open, $f_0$ = 10 MHz, $\overline{CE}$ = GND | One bit switching at $f_1$ = 5 MHz at 50% duty cycle | $V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V | | | | | 0.7 | 1.4 | |
| | | | $V_{IN}$ = 3.4 V or GND | | | | | 1.2 | 3.4 | |
| | | Eight bits switching at $f_1$ = 2.5 MHz at 50% duty cycle | $V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V | | | | | 1.6 | 3.2‖ | |
| | | | $V_{IN}$ = 3.4 V or GND | | | | | 3.9 | 12.2‖ | |
| $C_i$ | | | | | 5 | 10 | | 5 | 10 | pF |
| $C_o$ | | | | | 9 | 12 | | 9 | 12 | pF |

† Typical values are at $V_{CC}$ = 5 V, $T_A$ = 25°C.

¶ This parameter is derived for use in total power-supply calculations.

# $I_C = I_{CC} + \Delta I_{CC} \times D_H \times N_T + I_{CCD} (f_0/2 + f_1 \times N_1)$

Where:

$I_C$ = Total supply current
$I_{CC}$ = Power-supply current with CMOS input levels
$\Delta I_{CC}$ = Power-supply current for a TTL high input ($V_{IN}$ = 3.4 V)
$D_H$ = Duty cycle for TTL inputs high
$N_T$ = Number of TTL inputs at $D_H$
$I_{CCD}$ = Dynamic current caused by an input transition pair (HLH or LHL)
$f_0$ = Clock frequency for registered devices, otherwise zero
$f_1$ = Input signal frequency
$N_1$ = Number of inputs changing at $f_1$

All currents are in milliamperes and all frequencies are in megahertz.

‖ Values for these conditions are examples of the $I_{CC}$ formula.

## timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

| | | | CY54FCT377AT CY54FCT377CT | | CY74FCT377T CY74FCT377AT CY74FCT377CT | | UNIT |
|---|---|---|---|---|---|---|---|
| | | | MIN | MAX | MIN | MAX | |
| $t_w$ | Pulse duration, CP high or low† | | 7 | | 6 | | ns |
| $t_{su}$ | Setup time, high or low | Data before CP↑ | 2 | | 2 | | ns |
| | | $\overline{CE}$ before CP↑ | 3.5 | | 3.5 | | |
| $t_h$ | Hold time, high or low | Data after CP↑ | 1.5 | | 1.5 | | ns |
| | | $\overline{CE}$ after CP↑ | 1.5 | | 1.5 | | |

† With one data channel switching, $t_{w(L)} = t_{w(H)} = 4$ ns and $t_r = t_f = 1$ ns.

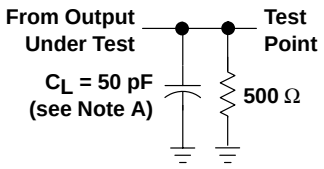
## switching characteristics over operating free-air temperature range (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | CY54FCT377AT | | CY54FCT377CT | | UNIT |
|---|---|---|---|---|---|---|---|
| | | | MIN | MAX | MIN | MAX | |
| $t_{PLH}$ | CP | O | 2 | 8.3 | 2 | 5.5 | ns |
| $t_{PHL}$ | | | 2 | 8.3 | 2 | 5.5 | |

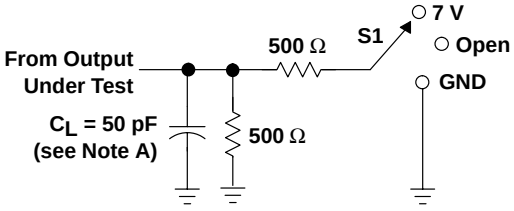
## switching characteristics over operating free-air temperature range (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | CY74FCT377T | | CY74FCT377AT | | CY74FCT377CT | | UNIT |
|---|---|---|---|---|---|---|---|---|---|
| | | | MIN | MAX | MIN | MAX | MIN | MAX | |
| $t_{PLH}$ | CP | O | 2 | 13 | 2 | 7.2 | 2 | 5.2 | ns |
| $t_{PHL}$ | | | 2 | 13 | 2 | 7.2 | 2 | 5.2 | |

## PARAMETER MEASUREMENT INFORMATION

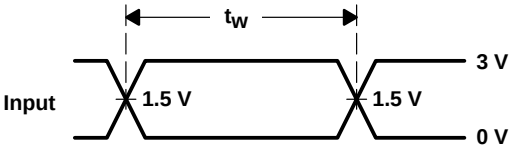



LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS

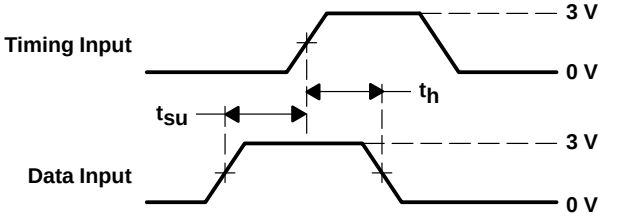



LOAD CIRCUIT FOR
3-STATE OUTPUTS

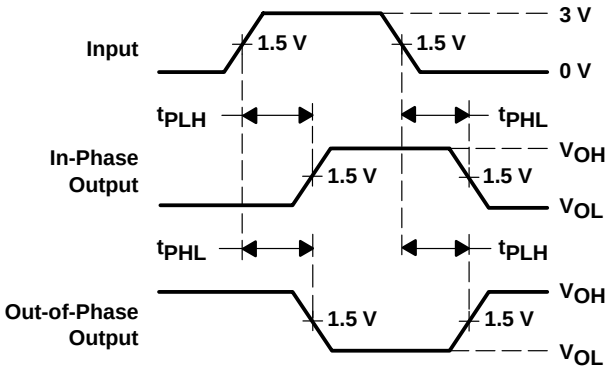
| TEST | S1 |
|---|---|
| $t_{PLH}/t_{PHL}$ | Open |
| $t_{PLZ}/t_{PZL}$ | 7 V |
| $t_{PHZ}/t_{PZH}$ | Open |



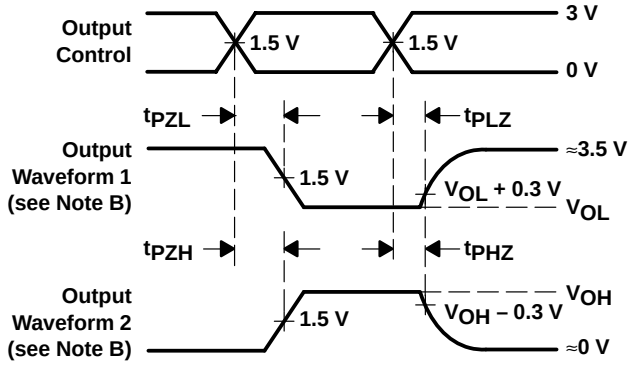

VOLTAGE WAVEFORMS
PULSE DURATION




VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES




VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS




VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. $C_L$ includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. The outputs are measured one at a time with one input transition per measurement.

**Figure 1. Load Circuit and Voltage Waveforms**

## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) |
|---|---|---|---|---|---|---|---|---|
| 5962-9221902M2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| 5962-9221903M2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| CY54FCT377CTLMB | ACTIVE | LCCC | FK | 20 | 1 | TBD | POST-PLATE | N / A for Pkg Type |
| CY74FCT377ATQCT | ACTIVE | SSOP/ QSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| CY74FCT377ATQCTE4 | ACTIVE | SSOP/ QSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| CY74FCT377ATQCTG4 | ACTIVE | SSOP/ QSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| CY74FCT377ATSOC | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CY74FCT377ATSOCE4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CY74FCT377ATSOCG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CY74FCT377ATSOCT | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CY74FCT377ATSOCTE4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CY74FCT377ATSOCTG4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CY74FCT377CTQCT | ACTIVE | SSOP/ QSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| CY74FCT377CTQCTE4 | ACTIVE | SSOP/ QSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| CY74FCT377CTQCTG4 | ACTIVE | SSOP/ QSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| CY74FCT377CTSOC | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CY74FCT377CTSOCE4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CY74FCT377CTSOCG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CY74FCT377CTSOCT | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CY74FCT377CTSOCTE4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CY74FCT377CTSOCTG4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CY74FCT377TQCT | ACTIVE | SSOP/ QSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| CY74FCT377TQCTE4 | ACTIVE | SSOP/ QSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| CY74FCT377TQCTG4 | ACTIVE | SSOP/ QSOP | DBQ | 20 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |

(1) The marketing status values are defined as follows:
**ACTIVE:** Product device recommended for new designs.
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

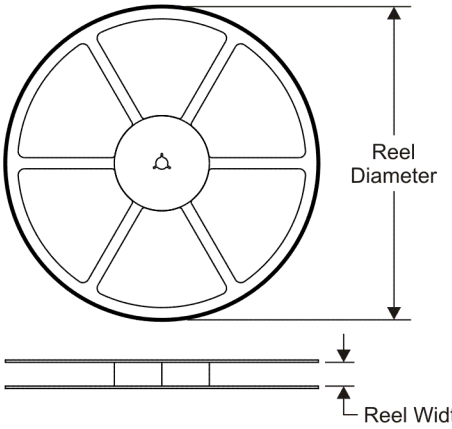
a new design.
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
**OBSOLETE:** TI has discontinued the production of the device.

**(2)** Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
**TBD:** The Pb-Free/Green conversion plan has not been defined.
**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

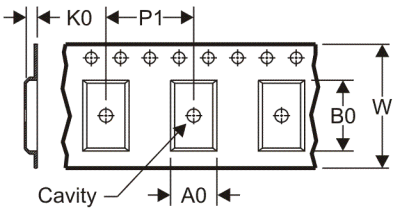
**(3)** MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

## TAPE AND REEL INFORMATION

**REEL DIMENSIONS**

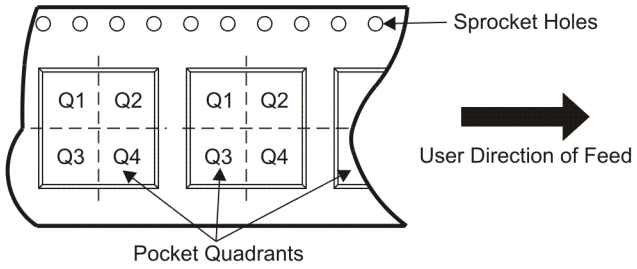



**TAPE DIMENSIONS**




| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

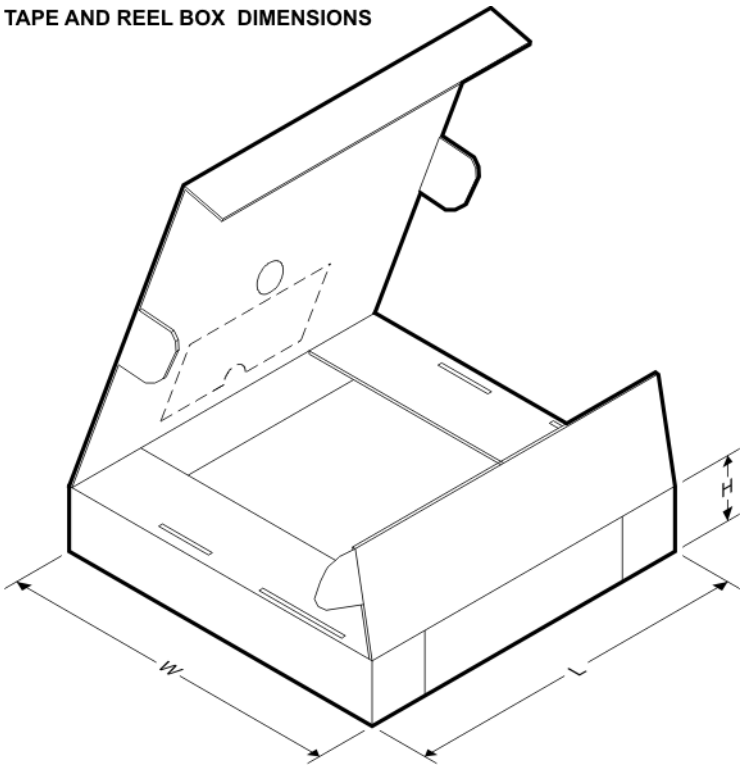
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| CY74FCT377ATQCT | SSOP/ QSOP | DBQ | 20 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CY74FCT377ATSOCT | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |
| CY74FCT377CTQCT | SSOP/ QSOP | DBQ | 20 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CY74FCT377CTSOCT | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |
| CY74FCT377TQCT | SSOP/ QSOP | DBQ | 20 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |

**TAPE AND REEL BOX DIMENSIONS**




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| CY74FCT377ATQCT | SSOP/QSOP | DBQ | 20 | 2500 | 346.0 | 346.0 | 33.0 |
| CY74FCT377ATSOCT | SOIC | DW | 20 | 2000 | 346.0 | 346.0 | 41.0 |
| CY74FCT377CTQCT | SSOP/QSOP | DBQ | 20 | 2500 | 346.0 | 346.0 | 33.0 |
| CY74FCT377CTSOCT | SOIC | DW | 20 | 2000 | 346.0 | 346.0 | 41.0 |
| CY74FCT377TQCT | SSOP/QSOP | DBQ | 20 | 2500 | 346.0 | 346.0 | 33.0 |

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